**TELEFUNKEN Semiconductors** 

### **MOSMIC®** For TV-Tuner Prestage With 9 V Supply Voltage

MOSMIC - MOS Monolithic Integrated Circuit

## Electrostatic sensitive device. Observe precautions for handling.



#### **Applications**

Low noise gain controlled input stages in UHF- and VHF-tuner with 9 V supply voltage.

# AGC G2RF in G1C block C block C block C block

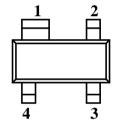
#### **Features**

- Integrated gate protection diodes
- Low noise figure
- High gain
- Biasing network on chip

94 9279

Improved cross modulation at gain reduction

- High AGC-range
- SMD package



94 9278

S949T Marking: 949 Plastic case (SOT 143)

1 = Source; 2 = Drain; 3 = Gate 2; 4 = Gate 1

S949TR Marking: 99 R Plastic case (SOT 143R)

1 = Source; 2 = Drain; 3 = Gate 2; 4 = Gate 1

#### **Absolute Maximum Ratings**

Parameters	Symbol	Value	Unit	
Drain source voltage	$V_{DS}$	12	V	
Drain current	$I_{D}$	30	mA	
Gate 1/gate 2-source peak current	±I <sub>G1/G2SM</sub>	10	mA	
Gate 1/gate 2-source voltage	$\pm V_{G1/G2SM}$	6	V	
Total power dissipation $T_{amb} \le 60^{\circ}C$	P <sub>tot</sub>	200	mW	
Channel temperature	$T_{Ch}$	150	°C	
Storage temperature range	$T_{ m stg}$	-55 to +150	°C	

#### **Maximum Thermal Resistance**

Parameters	Symbol	Maximum	Unit
Channel ambient on glass fibre printed board			
$(25 \times 20 \times 1.5) \text{ mm}^3 \text{ plated with } 35  \mu\text{m} \text{ Cu}$	$R_{thChA}$	450	K/W

#### **Electrical DC Characteristics**

 $T_{amb} = 25^{\circ}C$ 

Parameters / Test Conditions	Symbol	Min.	Тур.	Max.	Unit
	±V <sub>(BR)G1SS</sub>	7.5		9.5	V
Gate 2-source breakdown voltage $\pm I_{G2S} = 10 \text{ mA}, V_{G1S} = V_{DS} = 0$	±V <sub>(BR)G2SS</sub>	7.5		9.5	V
Gate 1-source leakage current $\pm V_{G1S} = 5 \text{ V}, V_{G2S} = V_{DS} = 0$	±I <sub>G1SS</sub>			50	μΑ
Gate 2-source leakage current $\pm V_{G2S} = 5 \text{ V}, V_{G1S} = V_{DS} = 0$	±I <sub>G2SS</sub>			20	nA
Drain current $V_{DS} = 9 \text{ V}, V_{G1S} = 0, V_{G2S} = 4 \text{ V}$	I <sub>DSS</sub>	50		500	μΑ
Self-biased operating current $V_{DS} = 9 \text{ V}, V_{G1S} = \text{nc}, V_{G2S} = 4 \text{ V}$	I <sub>DSP</sub>	8	12	16	mA
Gate 2-source cut-off voltage $V_{DS} = 9 \text{ V}, V_{G1S} = \text{nc}, I_D = 100 \mu\text{A}$	V <sub>G2S(OFF)</sub>		1		V

#### **Electrical AC Characteristics**

 $V_{DS} = 9 \text{ V}, V_{G2S} = 4 \text{ V}, f = 1 \text{ MHz}, T_{amb} = 25^{\circ}\text{C}$ 

Parameters / Test Conditions	Symbol	Min.	Тур.	Max.	Unit
Forward transadmittance	$ y_{21s} $	25	30	35	mS
Gate 1 input capacitance	C <sub>issg1</sub>		2.3	2.7	pF
Feedback capacitance	$C_{rss}$		25		fF
Output capacitance	C <sub>oss</sub>		1		pF
$\label{eq:power gain} \begin{array}{l} \text{Power gain} \\ \text{g}_S = 2 \text{ mS},  \text{g}_L = 0.5 \text{ mS},  \text{f} = 200 \text{ MHz} \\ \text{g}_S = 3.3 \text{ mS},  \text{g}_L = 1 \text{ mS},  \text{f} = 800 \text{ MHz} \end{array}$	$rac{G_{ m ps}}{G_{ m ps}}$	17	28 20		dB dB
AGC range $V_{DS} = 9 \text{ V}, V_{G2S} = 1 \text{ to } 4 \text{ V}, f = 800 \text{ MHz}$	$\Delta G_{ m ps}$	45			dB
Noise figure $g_S=2 \text{ mS}, g_L=0.5 \text{ mS}, f=200 \text{ MHz} \\ g_S=3.3 \text{ mS}, g_L=1 \text{ mS}, f=800 \text{ MHz}$	F F		1 1.3		dB dB

#### **Caution for Gate 1 switch-off mode:**

No external DC-voltage on Gate 1 in active mode! Switch-off at Gate 1 with  $V_{G1S} < 0.7 \text{ V}$  is feasible.

Using open collector switching transistor (inside of PLL), insert 10 k $\Omega$  collector resistor.

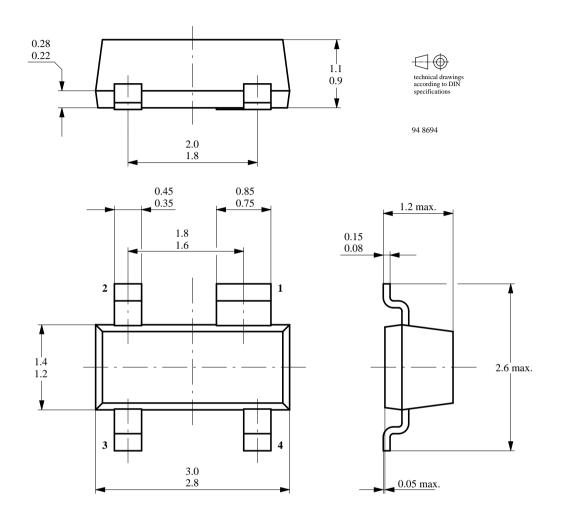
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#### **Common Source S-Parameters**

 $V_{DS} = 9 V$ ;  $V_{G2S} = 4 V$ 

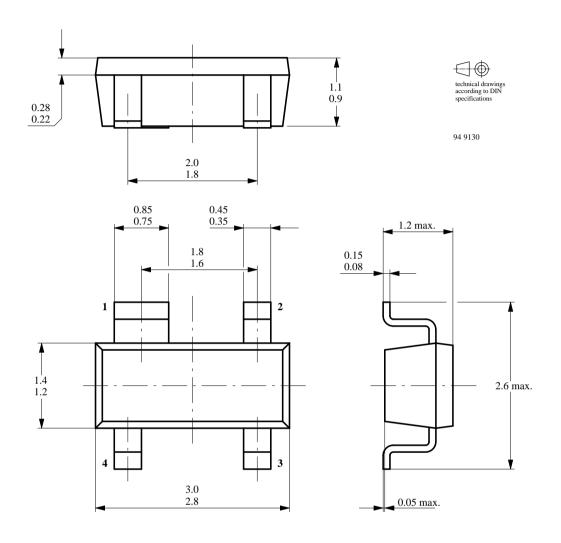
	$S_1$	1	S <sub>21</sub>		S <sub>12</sub>		S <sub>22</sub>	
f/MHz	LOG MAG	ANG	LOG MAG	ANG	LOG MAG	ANG	LOG MAG	ANG
	dB	deg	dB	deg	dB	deg	dB	deg
50	-0.02	-4.1	7.50	174.9	-63.74	88.2	-0.13	-1.6
100	-0.04	-7.9	7.41	169.0	-57.58	85.0	-0.14	-3.0
150	-0.12	-11.9	7.31	162.9	-54.15	82.1	-0.16	-4.5
200	-0.19	-15.7	7.20	157.3	-51.78	79.3	-0.18	-5.8
250	-0.29	-19.7	7.07	150.8	-50.15	76.8	-0.20	-7.6
300	-0.41	-23.1	6.94	145.8	-48.89	75.0	-0.24	-8.9
350	-0.52	-26.8	6.71	140.0	-47.92	72.9	-0.27	-10.2
400	-0.66	-30.3	6.59	134.8	-47.25	71.2	-0.31	-11.7
450	-0.81	-33.6	6.34	129.9	-46.77	69.8	-0.35	-12.9
500	-0.97	-36.9	6.17	124.6	-46.47	68.5	-0.40	-14.5
550	-1.12	-40.3	5.96	119.7	-46.32	67.8	-0.44	-15.7
600	-1.28	-43.3	5.74	114.7	-46.34	68.8	-0.49	-17.0
650	-1.42	-46.5	5.55	110.6	-46.24	70.0	-0.54	-18.2
700	-1.55	-49.6	5.36	105.8	-46.36	71.0	-0.57	-19.4
750	-1.70	-52.4	5.17	101.5	-46.67	72.9	-0.62	-20.8
800	-1.87	-55.4	4.98	97.0	-47.12	76.2	-0.66	-22.0
850	-1.99	-58.4	4.84	93.0	-47.41	81.6	-0.71	-23.3
900	-2.11	-61.3	4.68	88.4	-47.72	89.3	-0.74	-24.8
950	-2.24	-64.2	4.52	84.5	-47.55	98.3	-0.79	-25.9
1000	-2.38	-67.1	3.31	80.3	-47.07	104.4	-0.86	-27.3
1050	-2.50	-69.9	4.14	75.8	-46.96	110.4	-0.95	-28.4
1100	-2.67	-72.8	3.96	71.9	-46.72	119.7	-0.98	-29.7
1150	-2.72	-75.7	3.90	67.6	-45.93	128.4	-1.01	-31.1
1200	-2.85	-78.5	3.80	64.2	-44.91	137.0	-1.03	-32.4
1250	-2.95	-81.4	3.67	60.0	-43.76	144.2	-1.06	-33.8
1300	-3.06	-84.4	3.55	55.7	-42.39	149.1	-1.15	-35.0

#### **Dimensions of S949T in mm**



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#### **Dimensions of S949TR in mm**



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#### **Ozone Depleting Substances Policy Statement**

It is the policy of **TEMIC TELEFUNKEN microelectronic GmbH** to

- 1. Meet all present and future national and international statutory requirements.
- 2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

**TEMIC TELEFUNKEN microelectronic GmbH** semiconductor division has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

- 1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
- 2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
- 3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

**TEMIC** can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

#### We reserve the right to make changes without further notice to improve technical design.

Parameters can vary in different applications. All operating parameters must be validated for each customer application by customer. Should Buyer use TEMIC products for any unintended or unauthorized application, Buyer shall indemnify TEMIC against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

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